## Polyimide Adhesive Tape HB830 TECHNICAL DATA

ITEM	UNIT	PROPERTY DATA
Structure	-	- Silicone Adhesive - Primer - PI Film
Base Film Thickness	μm	25 ± 2 ASTM D3652
Total Thickness	μm	70 ± 3 ASTM D3652
Peel Strength	gf/25mm	600 ± 100 ASTM D3330
Tensile Strength	kg/25mm	15 ~ 17 ASTM D3759
Elongation	%	85 ~ 95 ASTM D3759
Breakdown Voltage	kv	7 ASTM D149
Temperature Use Range	-	-50°C ~ 260°C Long Term >260°C Short Term
Chemical Resistance	-	Good (20% HCI, NaOH / 20hrs)

Unless stated otherwise all values given are average. All of the tapes in our range should be thoroughly tested on the substrates in the particular application they are intended for. Hi-Bond Tapes Ltd. will not be responsible for product failure unless full testing has been completed. The customer has to decide on the tapes suitability for the intended application.